



Tuesday, May 15, 2012 (day one)

- 7:30 Registration
- 8:30 Welcome to the Conference – ASMC 2012 Conference Chairs  
Jennifer Braggin, Entegris and Larry Pulvirent, GLOBALFOUNDRIES  
ASMC 2011 Best Paper and Best Student Paper Awards
- 8:45 Keynote: Michael Campbell, VP Engineering, Qualcomm  
*“Semiconductor Customer Perspective”*

Session 1 - Yield Enhancement (in parallel with Session 2)

Chairs: Gary Green, Green Consulting; Christopher Hess, PDF Solutions

Defect inspection, yield analysis and optimization are integral components in the development and manufacture of semiconductor devices. This session reviews optimizing and maximizing product yield and intelligently isolating faults

9:50

- 1.1 Identifying Systematic Critical Features Using Silicon Diagnosis Data  
Chris Schuermyer, Mentor Graphics; Shobhit Malik, Thomas Herrmann, GLOBALFOUNDRIES

10:20

- 1.2 Using Selective Voltage Binning to Maximize Yield  
Susan Lichtensteiger, Jeanne Paulette Bickford, IBM Systems and Technology Group

10:45 Break

11:00

- 1.3 Analytic Modeling of AC Response to FET-level Elements for CLY Optimization  
Gauri Karve, Ron Logan, Brian Greene, Jonathan Winslow, IBM Systems and Technology Group

11:25

- 1.4 Optimizing Product Yield Using Manufacturing Defect Weights  
Jeanne Paulette Bickford, Jason D. Hibbeler, Sven Peyer, Vasanth S. Kumar, IBM STG; Dirk Mueller, University of Bonn

11:50

- 1.5 Improving Yield Learning by Electrical Fault Inspection  
Jeffrey A. Block, Paul Sakamoto, Ted Lundquist, DCG Systems, Inc.

12:15 Networking Lunch